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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/698,704	10/31/2003	Robert O. Conn	X-1416-3 US	1939
24309	7590	09/20/2007	EXAMINER	
XILINX, INC ATTN: LEGAL DEPARTMENT 2100 LOGIC DR SAN JOSE, CA 95124			WILLIAMS, ALEXANDER O	
ART UNIT		PAPER NUMBER		
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09/20/2007		PAPER		

Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

Office Action Summary	Application No.	Applicant(s)	
	10/698,704	CONN, ROBERT O.	
	Examiner	Art Unit	
	Alexander O. Williams	2826	

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --
Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

1) Responsive to communication(s) filed on 09 April 2007.
 2a) This action is FINAL. 2b) This action is non-final.
 3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

4) Claim(s) 1-8 and 12-16 is/are pending in the application.
 4a) Of the above claim(s) _____ is/are withdrawn from consideration.
 5) Claim(s) _____ is/are allowed.
 6) Claim(s) 1-8 and 12-16 is/are rejected.
 7) Claim(s) _____ is/are objected to.
 8) Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

9) The specification is objected to by the Examiner.
 10) The drawing(s) filed on _____ is/are: a) accepted or b) objected to by the Examiner.
 Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
 Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
 11) The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
 a) All b) Some * c) None of:
 1. Certified copies of the priority documents have been received.
 2. Certified copies of the priority documents have been received in Application No. _____.
 3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

* See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

1) Notice of References Cited (PTO-892)
 2) Notice of Draftsperson's Patent Drawing Review (PTO-948)
 3) Information Disclosure Statement(s) (PTO/SB/08)
 Paper No(s)/Mail Date _____

4) Interview Summary (PTO-413)
 Paper No(s)/Mail Date _____
 5) Notice of Informal Patent Application
 6) Other: _____

Serial Number: 10/698704 Attorney's Docket #: X-1416-3US
Filing Date: 10/31/2003;

Applicant: Conn

Examiner: Alexander Williams

Applicant's Response filed 4/9/07 to the election of Group I (claims 1 to 8 and 12 to 16) filed 6/29/05 to the species elected of species of figures 1 to 7 filed 4/4/05 has been acknowledged.

Claims 9-11 have been cancelled.

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless –

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

(e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.

Claims 1- 8 and 12-16, insofar as they can be understood, are rejected under 35 U.S.C. 102(e) as being anticipated by Chung et al. (U.S. Patent # 6,680,218 B2).

1. Chung et al. (figures 1 to 11) specifically figure 5 show an assembly, comprising: an integrated circuit die 302 having an array of micro-bumps (bumps between 302 and 304) disposed on a surface of the integrated circuit die in a first pattern; an integrated circuit package 306 having an array of landing pads (pads on the top surface of 306) disposed on an inside surface of the integrated

circuit package in a second pattern and array of solder balls 142 disposed on an outside surface of the integrated circuit package, wherein the first pattern and the second pattern are substantially identical patterns; and an interposing structure 304 disposed inside the integrated circuit package between the integrated circuit die and the inside surface of the integrated circuit package, the interposer coupling a first micro-bump in a first position in the array of micro-bumps to a first landing pad (pads not labeled but shown) located opposite to the first position and to a second landing pad (pads not labeled but shown) in the array of landing pads.

2. The assembly of claim 1, Chung et al. show wherein a line extending through the first micro-bump in a direction orthogonal to the surface of the integrated circuit does not extend through the second landing pad of the integrated circuit package.
3. The assembly of claim 2, Chung et al. show wherein the surface of the integrated circuit die is a major surface of the integrated circuit die, and wherein the interposing structure has a major surface, and wherein the major surface of the integrated circuit die and the major surface of the interposing structure have roughly identical surface areas.
4. The assembly of claim 3, Chung et al. show wherein the interposing structure includes no transistor and no PN junction.
5. The assembly of claim 4, Chung et al. show wherein the interposing structure comprises an array of micro-bumps, wherein the array of micro-bumps of the interposing structure has a pattern that is substantially identical to the second pattern of the landing pads on the inside surface of the integrated circuit package.

6. The assembly of claim 5, Chung et al. show wherein the interposing structure includes a layer comprising epoxy and fiberglass.
7. The assembly of claim 5, Chung et al. show wherein the interposing structure includes a bypass capacitor **308**.
8. The assembly of claim 5, Chung et al. show wherein the first micro-bump is coupled to the first landing pad at least in part by a conductor disposed in the interposing structure, wherein the conductor disposed in the interposing structure extends in a direction parallel to the surface of the integrated circuit.
12. Chung et al. (figures 1 to 11) specifically figure 5 show an assembly, comprising: an integrated circuit die **302** having an array of micro-bumps (**bumps between 302 and 304**) disposed on a surface of the integrated circuit die in a first pattern; an integrated circuit package **306** having an array of landing pads disposed on an inside surface of the integrated circuit package in a second pattern, wherein the first pattern and the second pattern are substantially identical patterns; the means **304** for coupling a first micro-bump in a first position in the array of microbumps to a first landing pad disposed opposed the first position and to a second landing pad located in a different position in the array of landing pads, the means being disposed inside the integrated circuit package between the integrated circuit die and the inside surface of the integrated circuit package.
13. The assembly of claim 12, Chung et al. show wherein the interposing structure includes a bypass capacitor **308**.
14. The assembly of claim 12, Chung et al. show wherein the surface of the integrated circuit die is a major surface of the integrated circuit die, and wherein the means has a major surface, and wherein the major surface of the integrated circuit die and the major surface of the means have roughly identical surface areas.
15. The assembly of claim 12, Chung et al. show wherein the means has a planar form and is less than 500 microns thick.
Note that the specification contains no disclosure of either the critical nature of the claimed dimensions or any unexpected results arising therefrom. Where patentability is said to be based upon particular chosen dimensions or upon another variable recited in a claim, the Applicant must show that the chosen dimensions are critical. In re Woodruff, 919 F.2d 1575, 1578, 16 USPQ2d 1934, 1936 (Fed. Cir. 1990).

16. The assembly of claim 12, Chung et al. show wherein the integrated circuit die is an application specific integrated circuit (ASIC).

(5) IC 302 could be any of a number of types of ICs. In one embodiment of the present invention, IC 302 is a microprocessor, although IC 302 could be an application specific integrated circuit (ASIC), memory device or many other types of devices in other embodiments.

Claims 1- 8 and 12-15, insofar as they can be understood, are rejected under 35 U.S.C. 102(b) as being anticipated by Chance et al. (U.S. Patent # 5,177,594).

1. Chance et al. (figures 1 to 21) specifically figure 1 show an assembly, comprising: an integrated circuit die 52 having an array of micro-bumps 56 disposed on a surface of the integrated circuit die in a first pattern; an integrated circuit package 54 having an array of landing pads (inherent) disposed on an inside surface of the integrated circuit package in a second pattern and array of solder balls (pins) disposed on an outside surface of the integrated circuit package, wherein the first pattern and the second pattern are substantially identical patterns; and an interposing structure 50 disposed inside the integrated circuit package between the integrated circuit die and the inside surface of the integrated circuit package, the interposer coupling a first micro-bump in a first position in the array of micro-bumps to a first landing pad (pads not labeled but shown) located opposite to the first position and to a second landing pad (inherent) in the array of landing pads.

2. The assembly of claim 1, Chance et al. show wherein a line extending through the first micro-bump in a direction orthogonal to

the surface of the integrated circuit does not extend through the second landing pad of the integrated circuit package.

3. The assembly of claim 2, Chance et al. show wherein the surface of the integrated circuit die is a major surface of the integrated circuit die, and wherein the interposing structure has a major surface, and wherein the major surface of the integrated circuit die and the major surface of the interposing structure have roughly identical surface areas.

4. The assembly of claim 3, Chance et al. show wherein the interposing structure includes no transistor and no PN junction.

5. The assembly of claim 4, Chance et al. show wherein the interposing structure comprises an array of micro-bumps, wherein the array of micro-bumps of the interposing structure has a pattern that is substantially identical to the second pattern of the landing pads on the inside surface of the integrated circuit package.

6. The assembly of claim 5, Chance et al. show wherein the interposing structure includes a layer comprising epoxy and fiberglass.

7. The assembly of claim 5, Chance et al. show wherein the interposing structure includes a bypass capacitor (**see figures 9 and 10**).

8. The assembly of claim 5, Chance et al. show wherein the first micro-bump is coupled to the first landing pad at least in part by a conductor disposed in the interposing structure, wherein the conductor disposed in the interposing structure extends in a direction parallel to the surface of the integrated circuit.

12. Chance et al. (figures 1 to 21) specifically figure 1 show an assembly, comprising: an integrated circuit die **52** having an array of micro-bumps **56** disposed on a surface of the integrated circuit die in a first pattern; an integrated circuit package **54** having an array of landing pads disposed on an inside surface of the integrated circuit package in a second pattern, wherein the first pattern and the second pattern are substantially identical patterns; the means **50** for coupling a first micro-bump in a first position in the array of microbumps to a first landing pad disposed opposed

the first position and to a second landing pad located in a different position in the array of landing pads, the means being disposed inside the integrated circuit package between the integrated circuit die and the inside surface of the integrated circuit package.

13. The assembly of claim 12, Chance et al. show wherein the interposing structure includes a bypass capacitor (**see figures 9 and 10**).

14. The assembly of claim 12, Chamce et al. show wherein the surface of the integrated circuit die is a major surface of the integrated circuit die, and wherein the means has a major surface, and wherein the major surface of the integrated circuit die and the major surface of the means have roughly identical surface areas.

15. The assembly of claim 12, Chance et al. show wherein the means has a planar form and is less than 500 microns thick.

Note that the specification contains no disclosure of either the critical nature of the claimed dimensions or any unexpected results arising therefrom. Where patentability is said to be based upon particular chosen dimensions or upon another variable recited in a claim, the Applicant must show that the chosen dimensions are critical. In re Woodruff, 919 F.2d 1575, 1578, 16 USPQ2d 1934, 1936 (Fed. Cir. 1990).

Response

Applicant's arguments filed 4/9/07 have been fully considered, but are moot in view of the new grounds of rejections detailed above.

The listed references are cited as of interest to this application, but not applied at this time.

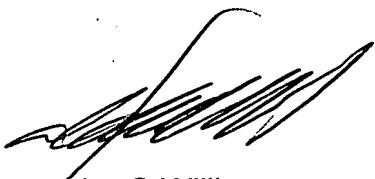
Field of Search	Date
U.S. Class and subclass: 257/653,758,774,778,737,738,734,686,685,723,691,774,6 92,693,700,e25.013,e23.125,e23.079,e23.026,e23.e23.06 3.e23.101,e23.181,e23.069,e23.126,e23.067,e23.062 361/306.3,312,313,321.1,321.4,763,748,762,760	9/11/05 4/13/06 7/24/06 12/23/06 9/13/07
Other Documentation: foreign patents and literature in 257/653,758,774,778,737,738,734,686,685,723,691,774,6 92,693,700,e25.013,e23.125,e23.079,e23.026,e23.e23.06 3.e23.101,e23.181,e23.069,e23.126,e23.067,e23.062 361/306.3,312,313,321.1,321.4,763,748,760,762	9/11/05 4/13/06 7/24/06 12/23/06 9/13/07

Electronic data base(s): U.S. Patents EAST	9/11/05 4/13/06 7/24/06 12/23/06 9/13/07
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Any inquiry concerning this communication or earlier communications from the examiner should be directed to Alexander O. Williams whose telephone number is (571) 272 1924. The examiner can normally be reached on M-F 6:30AM-7:00PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Nathan Flynn can be reached on (571) 272 1915. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).



Alexander O Williams
Primary Examiner
Art Unit 2826

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